Major Ratings and Characteristics

$I_{F(AV)}$	3.0 A
V_{RRM}	20 V to 100 V
I_{FSM}	80 A
V_F	0.55 V , 0.70 V, 0.85V
T_j max.	150 ℃

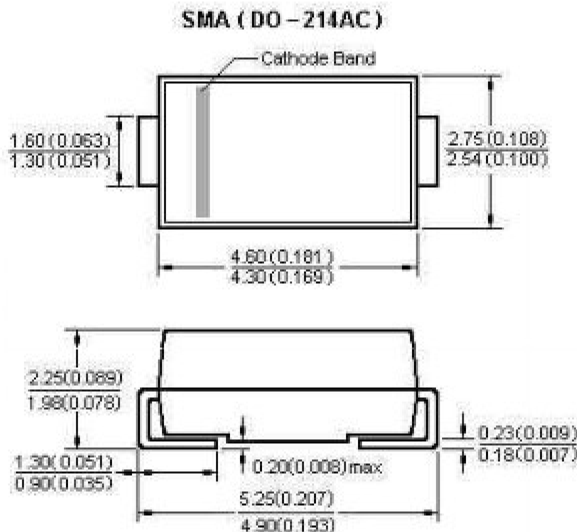
SMA (DO－214AC)

Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperatrue soldering：
  260℃/10 seconds at terminals
- Component in accordance to
  RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Date

- Case: JEDEC DO-214ACmolded plastic body over passivated chip
- Terminals: Solder plated, solderable per



Dimentsions in millimeters and (inchs)